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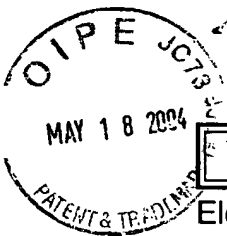
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Electronic Patent Application Submission
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EFS ID: 61214
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Title of Invention: LEADFRAME FOR
SEMICONDUCTOR PACKAGE
First Named Inventor: HYUNG LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-02-09
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Confirmation number: 8761
Attorney Docket Number: AMKOR006C




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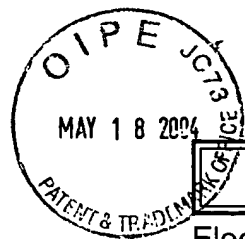
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Stylesheet Version v1.1.0

Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
us-ids	ids6-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

LEADFRAME FOR SEMICONDUCTOR PACKAGE

Application Number: 10/774893



Confirmation Number: 8761

First Named Applicant: HYUNG LEE

Attorney Docket Number: AMKOR006C

Art Unit: 2811

Search string: (6348726 or 6355502 or 6369447 or 6369454
or 6373127 or 6380048 or 6384472 or 6388336
or 6395578 or 6410979 or 6400004 or 6414385
or 6420779 or 6429508 or 6437429 or 6444499
or 6448633 or 6452279 or 6459148 or 6464121
or 6476469 or 6476474 or 6482680 or 6498099
or 6498392 or 6507096 or 6507120 or 6534849
or 6545332 or 6545345 or 6559525 or 6566168
or 6583503 or 6667546).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6348726	2002-02-19	Bayan et al.			
	2	6355502	2002-03-12	Kang et al.			
	3	6369447	2002-04-09	Mori			
	4	6369454	2002-04-09	Chung			
	5	6373127	2002-04-16	Baudouin et al.			
	6	6380048	2002-04-30	Boon et al.			
	7	6384472	2002-05-07	Huang			
	8	6388336	2002-05-14	Venkateshwaran et al.			
	9	6395578	2002-05-28	Shin et al.			
	10	6410979	2002-06-02	Abe			
	11	6400004	2002-06-04	Fan et al.			
	12	6414385	2002-07-02	Huang et al.			
	13	6420779	2002-07-16	Sharma et al.			



	14	6429508	2002-08-06	Gang
	15	6437429	2002-08-20	Su et al.
	16	6444499	2002-09-03	Swiss et al.
	17	6448633	2002-09-10	Yee et al.
	18	6452279	2002-09-17	Shimoda
	19	6459148	2002-10-01	Chun-Jen et al
	20	6464121	2002-10-15	Reijnders
	21	6476469	2002-11-05	Huang et al.
	22	6476474	2002-11-05	Hung
	23	6482680	2002-11-19	Khor et al.
	24	6498099	2002-12-24	McLellan et al.
	25	6498392	2002-12-24	Azuma
	26	6507096	2003-01-14	Gang
	27	6507120	2003-01-14	Lo et al.
	28	6534849	2003-03-18	Gang
	29	6545332	2003-04-08	Huang
	30	6545345	2003-04-08	Glenn et al.
	31	6559525	2003-05-06	Huang
	32	6566168	2003-05-20	Gang
	33	6583503	2003-06-24	Akram et al.
	34	6667546	2003-12-23	Huang et al.

Signature

Examiner Name	Date